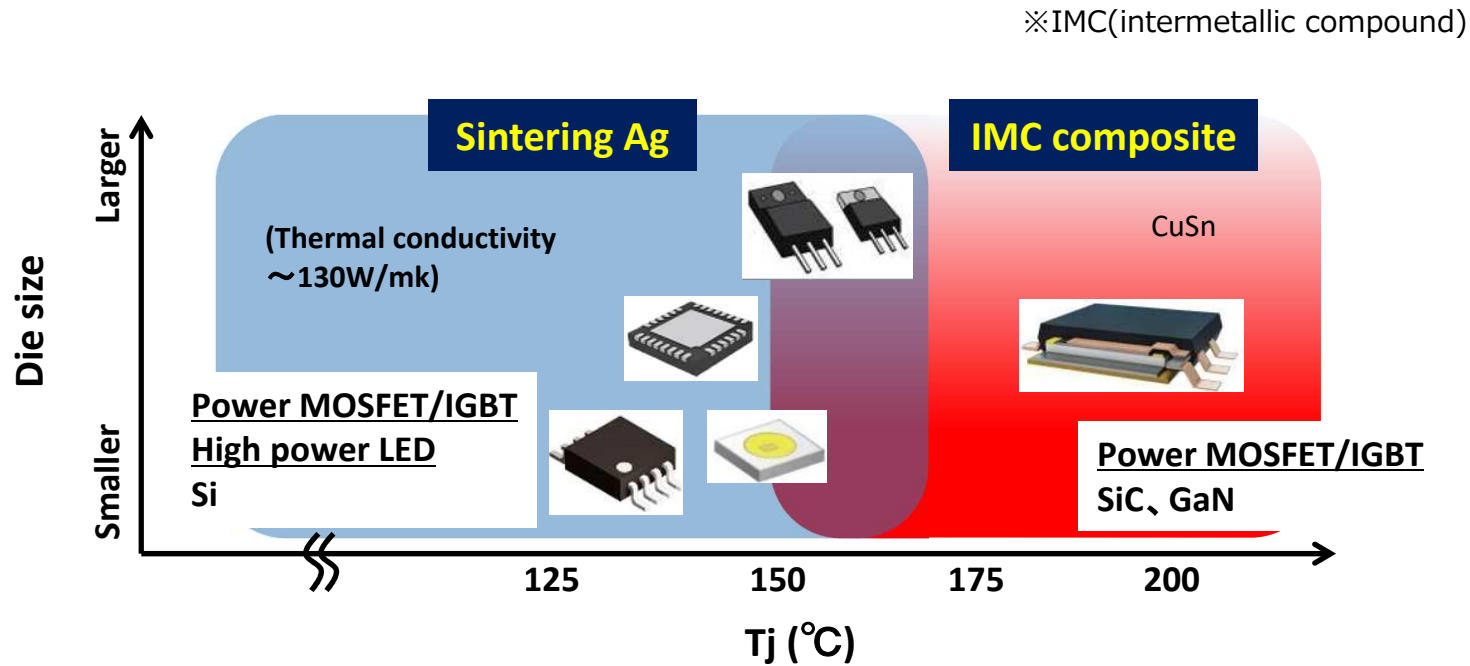


Paste for power semiconductor

Die Attach Paste for power semiconductors

Under Development

■ Target



Package: TO-252, power QFN/DFN, SOP, etc.
Application : Industry, Automotive, IPM modules, etc.

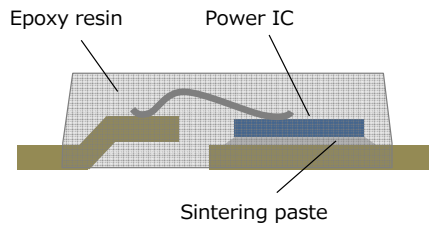
Die Attach Paste for power semiconductors

Under Development

■ TCT results(Sintering Ag paste)

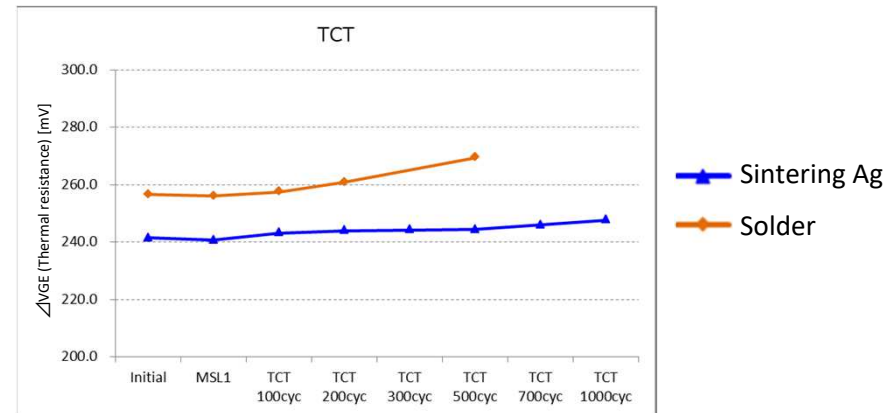
Test Package

- Package type : TO-252-2
- Lead frame : Cu Frame/0.5mmt/PPF plated
- Die : Si IGBT (Backside metal=Final Au)
- Die size : 3.00×2.50×0.40mmt



Average change thermal resistance

TCT conditions : -65°C (15min.) ~150°C (15min.) n=30



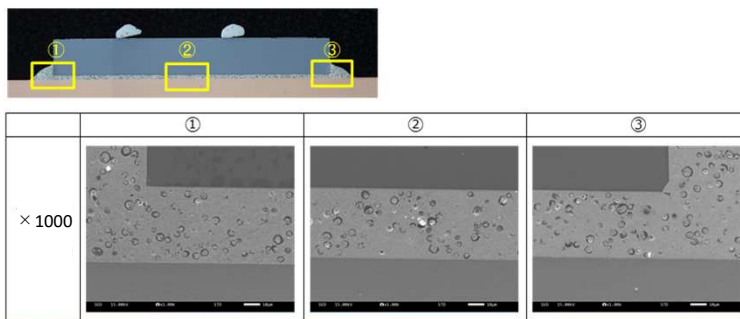
Average rate of change from initial to TCT 500cycle

Solder : 5.0% Sintering Ag : 1.2%

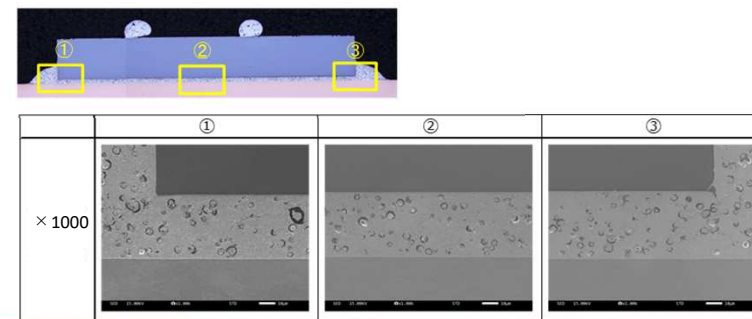
Sintering Ag has low initial thermal resistance, the rate of change in thermal resistance is smaller than Solder.

Cross section

Initial



After TCT 500cycle



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